Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in this application.

Listing of Claims:

1. (Original) A stencil printing master comprising:

a porous fiber layer; and

a porous resin layer formed on one surface of the porous fiber layer, the porous resin layer comprising a thermoplastic resin having a ratio (G1/G2) of a storage modulus (G1) at 45°C to a storage modulus (G2) at 180°C of 1×10^2 to 1×10^4, and a peak melting temperature by DSC of 50°C to 150°C.

2. (Original) The stencil printing master according to claim 1, wherein the thermoplastic resin is at least one of an ionomer resin and an olefin resin.

3. (Original) The stencil printing master according to claim 1, wherein, in a case where the porous resin layer includes a resin other than the thermoplastic resin, the thermoplastic resin has a melting energy that is 70% or more of the total melting energy of all the resins.

4. (Original) The stencil printing master according to claim 1, wherein the master has a basis weight of 35 g/m^2 or more and an air permeability of 100 sec or less.

5. (Original) The stencil printing master according to claim 1, wherein the average pore size

of pores on the surface of the porous resin layer is 2μm to 10μm and the proportion of the area occupied by the pores is 30% to 90%.

6. (Original) The stencil printing master according to claim 1, wherein the master includes as a mold-release agent a silicone surfactant having an HLB value of at least 5.

7. (Original) The stencil printing master according to claim 1, wherein it is used for stencil printing employing an ink having a viscosity of 0.001 to 1 Pa·s.

8. (Currently amended) A process for producing a stencil printing master having a porous fiber layer; and a porous resin layer formed on one surface of the porous fiber layer, the porous resin layer comprising a thermoplastic resin having a ratio (G1/G2) of a storage modulus (G1) at 45°C to a storage modulus (G2) at 180°C of 1 x 10^2 to 1 x 10^4, and a peak melting temperature by DSC of 50°C to 150°C ~~according to claim 1~~, the process comprising:

(1) preparing a coating solution comprising a thermoplastic resin having a ratio (G1/G2) of a storage modulus (G1) at 45° C to a storage modulus (G2) at 180°C. of 1 x 10^2 to 1 x 10^4, and a peak melting temperature by DSC of 50°C to 150°C;

(2) introducing air bubbles into the coating solution by a mechanical stirring method; and

(3) coating one surface of a porous fiber layer with the air bubble-containing coating solution so as to form a porous resin layer.